

Electronic Patent Application Fee Transmittal

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|---|--------------------------------|-----------------|---------------|-----------------------------|
| Application Number: | 10731995 | | | |
| Filing Date: | 09-Dec-2003 | | | |
| Title of Invention: | PACKAGES FOR SEMICONDUCTOR DIE | | | |
| First Named Inventor: | Todd O. Bolken | | | |
| Filer: | J. Mike Amerson/Mary Paul | | | |
| Attorney Docket Number: | 6047-67518 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Statutory disclaimer | 1814 | 1 | 130 | 130 |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 130 |